

Product Terratek<sup>®</sup> BD1216

**Product Description** Proprietary blend of natural and synthetic biodegradable polyesters suitable for injection molding. This resin is made from polymers which pass industry standards for Industrial composting.

Nellewable content		
Biobased content (ASTM D6866)	60%	
Biomass content (by weight)	60%	

Renewable Conten

Property	Test Method	Value
Specific Gravity	ASTM D792	1.62
Shrinkage	ASTM D955	0.009 in/in
Melt Index (190°C / 2.16 kg)	ASTM D1238	30 g/10 min
Tensile Strength	ASTM D638	4,846 psi
Tensile Modulus	ASTM D638	414,338 psi
Elongation	ASTM D638	1.94%
Notched Izod Impact	ASTM D256	0.32 ft-lb/in
Flexural Strength	ASTM D790	9,059 psi
Flexural Modulus	ASTM D790	369,272 psi

## **Drying Conditions**

Moisture level: at or below 0.04% (400 ppm) Method: Karl Fischer; if using a loss in weight analyzer, contact Green Dot for more information.

Drying conditions: Desiccant dryer 140°F for 2 to 4 hours or until the recommended moisture level is reached

ATTENTION: Moisture in Terratek<sup>®</sup> BD resins may result in hydrolysis which can cause brittleness, loss in strength, and reduction in melt strength, in addition to potentially impacting the shelf life of finished parts.

## **Packaging and Storing**

This resin is typically packaged in a sealed plastic or foil lined box, drum, or gaylord. The product should be stored in a cool, dry, and sanitary area to achieve maximum stability.

## **Molding Recommendations**

Terratek<sup>®</sup> resins can be processed on conventional molding equipment. Follow standard purging process with a polyolefin or purge compound, such as Dyna-Purge, etc. Melt temperature of the resin should remain below 400°F.

Feed Zone	280°F to 320°F
Middle Zones	320°F to 360°F
Front Zones	320°F to 360°F
Nozzle/Die	320°F to 360°F
Mold	80°F to 120°F

The information and recommendations in this sheet are based on our experience and analysis using standard procedures, and are believed to be accurate and reliable. However, they serve merely as typical guides, and are presented in good faith for the benefit of our customers. No guarantee, expressed or implied, is made regarding accuracy of the analysis, patent infringement, liabilities, or risks involved from the application